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電機學院通訊與網路科技產業研發碩士班

碩士論文

有效控制靜態耗電流之高功率高線性度 AB 類音頻放大器

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High Output-Power High Linearity CMOS Class AB Audio Amplifier with Quiescent Current Control

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中華民國九十六年七月

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摘 要

隨著行動化個人多媒體時代的來臨,具有較高功率轉換效率之D類音 頻放大器逐漸的備受重視。但是其線性度較差的缺點往往需要透過較複雜 的時脈調變機制或是補償控制來彌補。這對於某些需求僅僅著重在高輸出 功率,高線性度,低失真的傳統應用來說,並不一定是最適合架構。

此篇論文將以業界的商用規格為目標,設計具有高輸出功率,低失真 之 AB 類線性音頻放大器。並包含音量控制,耳機輸出,短路保護等功能。

一般而言,線性音頻放大器之負載阻抗約為8歐姆,輸出級必須具備 極大的電流驅動能力。輸出級的設計對放大器的靜態耗電流、功率轉換效 率與線性度有決定性的影響。本論文創新之處在於利用精簡的架構控制輸 出級之靜態耗電流,避免靜態耗電流與線性度受到製程漂移之影響,造成 不穩定的現象。此AB類輸出級的架構採用共源極組態之功率電晶體並搭 配誤差放大器,藉由降低誤差放大器之增益達到控制靜態耗電流的目標。 此誤差放大器之增益將隨著輸出功率增加而提高,當增益提高時,線性度 也隨之上升。另外,誤差放大器寬廣的輸出共模範圍,使受其控制的功率 電晶體可以用較小的面積達到所需的輸出功率。

晶片製作是採用聯華電子 0.5um +/-20V2P2M 製程。並且可在寬廣供應 電壓範圍 10~18V 之間使用。當供應電壓為 18V,負載為 8 歐姆,輸出功 率為 2W 時,總諧波失真大約為 0.060 %

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ABSTRACT

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With the advent of a highly-mobilized and individualized multimedia age, Class-D audio amplifiers with better power efficiency, among the applications of its kind, have gained a lot of attentions. However, in view of the fact that traditionally high output power, good linearity, and low distortion are expected in amplifiers alike, Class-D audio amplifiers may not be an ideal choice since it requires a complicated clock modulation or a compensatory control mechanism to make up to its poor output linearity. To look for an applicable alternative, therefore, this thesis puts forth a Class-AB linear audio amplifier that not only meets the design specification of business application, but also equips with features such as volume control, earphone output ports, short-circuit protection, and other functions desired in a multimedia product.

In general, a linear audio amplifier has a load impedance of approximately 8 ohm, so its output stage must have a compatibly large current drive, whose design has a significant influence on the quiescent current, power efficiency, and linearity. These deciding factors in designing a linear audio amplifier thus reveal the originality of this thesis: to rid the unwanted quiescent current of the output

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stage and unstable linearity resulted from process variation with a succinct structure. The Class-AB output stage adopts common-source power transistors with error amplifiers. By decreasing the gain of the error amplifier, the quiescent current is successfully controlled. Since the gain of the error amplifier will increase as the output power rises, it will therefore enhance the linearity. Besides, its output common mode range is the same as the supply voltage, which is sufficient enough to drive a smaller-sized power transistor to achieve the desired output power.

The chip is fabricated by the UMC 0.5um +/-20V2P2M high voltage process. It could undertake a high supply voltage ranging from 10V to 18V. The total harmonic distortion is approximately 0.060 % provided that the load impedance is 8 ohm and the output power is 2 watt under an 18V supply voltage.



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CHAPTER 1

Introduction

1.1 Background

With the advent of a highly-mobilized and individualized multimedia age, Class-D audio amplifiers with better power efficiency, among the applications of its kind, have gained a lot of attentions. However, in view of the fact that traditionally high output power, good linearity, and low distortion are expected in amplifiers alike, Class-D audio amplifiers may not be an ideal choice since it requires a complicated clock modulation or a compensatory control mechanism to make up to its poor output linearity.

Take audio amplifier applications, such as flat panel monitors and flat panel TVs, for example. These systems are usually equipped with a considerably high DC voltage source of 12V, 18V, or even 40V in order to drive their LCD display devices. In these cases, instead of using the relatively more complicated Class-D amplifiers, applying linear audio amplifiers would simply result in a high output power and high linearity as expected.

Most audio amplifiers have very small output resistance load, usually somewhere between 4 to 32Ω . Therefore, to ensure a desired amount of signal power delivery at the load with signal distortion within tolerance, the output stage usually consists of a voltage buffer with high input impedance and very low output impedance. Generally, these linear output stages can be divided into three categories [1], as shown in Table1-1. Among the three, Class-AB output stage, with better power efficiency and satisfactory linearity, is by far more applicable in practice. Therefore, we will next introduce some Class-AB output stage structures in the hope that we can compare them with structures of other kinds to find out their

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advantages and disadvantages.

Туре	Maximum power efficiency	Linearity	Characteristic
Class-A	<25%	Good	Poor power efficiency
Class-B	<78.5%	Poor	Crossover distortion
Class-AB	25% ~ 78.5%	Good	Suitable performance

Table 1-1 Comparison of linear output stage

1.1.1 Review of the class-AB output stage architecture



With the body effect ignored, $V_{GS3} + |V_{GS4}|$ is constant if the bias current I_{B1} is constant.

Under these conditions, increasing V_{GS1} decreases $|V_{GS2}|$ and vice versa. Assume all devices have same threshold voltage in the quiescent condition. Equation 1.1 can be re-written as

$$\sqrt{\frac{2I_{D1}}{k'_{n}(W/L)_{1}}} + \sqrt{\frac{2I_{|D2|}}{k'_{p}(W/L)_{2}}} = \sqrt{\frac{2I_{B1}}{k'_{n}(W/L)_{3}}} + \sqrt{\frac{2I_{B1}}{k'_{p}(W/L)_{4}}}$$
(1.2)

If $V_o = \frac{V_{DD} - V_{SS}}{2}$, then $I_{D2} = -I_{D1}$ and (1.2) can be rearranged to give

$$I_{D1} = I_{D4} \left(\frac{1/\sqrt{k_n'(W/L)_3} + 1/\sqrt{k_p'(W/L)_4}}{1/\sqrt{k_n'(W/L)_1} + 1/\sqrt{k_p'(W/L)_2}} \right)^2$$
(1.3)

The key point of equation 1.3 is that the quiescent current in the output transistors is

well-controlled with respect to the bias current that flows in the diode-connected transistors. .An important problem with this circuit is that its output swing is limited by the source follower configuration at the output node. Assume $V_{ss} = -V_{DD}$ $V_o < 0$, $V_{sg2} > |V_{t2}|$, and M_2 acts as a source follower. Therefore,

$$V_{O(\min)} = V_{SS} + V_{OV5} + V_{sg2} = -V_{DD} + V_{OV5} + V_{sg2}$$
(1.4)

The maximum output voltage can be derived by similar reasoning. From (1.4), the output swing can't reach the supply voltage, and the difference varies with the biasing condition. Since the source is the output node, the MOS device becomes dependent on the body effect. The body effect causes the threshold voltage $|V_{t2}|$ to increase as the output voltage is decreased. Also, the source-gate overdrive voltage rises while the output current increases. In practice, the output voltage swing can be increased by increasing the W/L ratios of the output devices to reduce their overdrives. However, in such doing, the required transistor sizes are sometimes too large to be economical.



Figure 1.1 Source follower Class-AB output stage.

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(2) Common-Source configuration

The problem of limited output swing in Common-Drain configuration can be improved by another alternative [2]. Fig.1.2 shows a Class-AB Push-Pull Common-Source output stage. Let $I_{B1} = I_{B2} = I_{B3}$, and $\frac{1}{K} \left(\frac{W}{L}\right)_1 = \left(\frac{W}{L}\right)_{11}$, $\left(\frac{W}{L}\right)_3 = \left(\frac{W}{L}\right)_{12}$, $\frac{1}{K} \left(\frac{W}{L}\right)_2 = \left(\frac{W}{L}\right)_{13}$, $\left(\frac{W}{L}\right)_4 = \left(\frac{W}{L}\right)_{14}$. Then, $V_{GS1} = V_{GS11}$, $V_{GS3} = V_{GS12}$, $V_{GS2} = V_{GS13}$, $V_{GS4} = V_{GS14}$, and $I_{Quiescent} = I_{D1} = I_{D2} = KI_{B1}$ (1.5)

Equation (1.5) shows that the quiescent current of this circuit can be controlled by the W/L ratio. M₃ and M₄ form a floating resistor which is biased by M₁₁, M₁₂, I_{B2} , and M₁₃, M₁₄, I_{B3} respectively. Compared with the aforementioned Common-Drain configuration, the output voltage in discussion here can reach ($V_{DD} - V_{OV1}$), or ($V_{ss} + V_{OV2}$) as the maximum output swing. M₁ and M₂ in the Common-Source Configuration form large output impedance at the output node. For general application, the pole at V_o can be significant. However, the loading impedance in a linear audio amplifier can be as small as 8 ohm. Such a large output impedance will cause serious signal loss and poor linearity.



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Figure 1.3 Common Source configuration of Class-AB output stage with error amplifier.

(3) Common-Source configuration with Error Amplifier

Another solution is the use of quasi-complementary configurations [1]. Fig.1.3 shows two comm.-source transistors together with two differential error amplifiers. The combination of the error amplifier and the common-source device simulates the behavior of a source follower with high dc transconductance. The function of the amplifier is to sense the voltage difference between the input and output of the stage and to drive the gates of the output transistors so as to minimize the voltage difference. This operation can also be viewed as a negative shunt feedback. A key advantage of the use of a negative feedback here is that it reduces the output resistance.



Figure 1.4 Small-signal model of the output stage in Fig.1.3

To find the output resistance, consider the small-signal model of this output stage shown in Fig 1.4. The transconductance G_o and output impedance are

$$G_{O} = -\frac{i_{O}}{V_{O}}\Big|_{V_{i=0}} = g_{m1}A_{EP} + g_{m2}A_{EN} + g_{O1} + g_{O2}$$
(1.6)

$$R_{o} = \frac{1}{g_{m1}A_{EP} + g_{m2}A_{EN}} / / r_{o1} / / r_{o2}$$
(1.7)

This equation shows that increasing the gain A of the error amplifier reduces R_o and that R_o is much smaller than the drain-source resistance of M₁ and M₂ because of the negative feedback.

Fig 1.5 shows the dc model which includes the input-referred offset voltages of the error amplifiers. Assume $-V_{tn} = V_{tp} = V_t$ and $k'_p (W/L)_1 = k'_n (W/L)_2 = k' (W/L)$. Also assume that the error amplifier are designed so that $I_Q = -I_{D1} = I_{D2}$ when $V_{OSP} = V_{OSN} = 0$ and $V_i = 0$. Under these conditions, $V_Q = 0$, $V_{QV} = \sqrt{\frac{2I_Q}{k'(W/L)}}$ and $V_{gs1} = -V_t - V_{QV}$,

 $V_{gs2} = V_t + V_{OV}$. With nonzero input and offsets, the output may not be zero. As a result, the differential input to the error amplifier EP changes from zero to $V_O - (V_i - V_{OSP})$. Similarly, the differential input to the error amplifier EN changes from zero to $V_O - (V_i - V_{OSP})$.

Assume that the output of each error amplifier changes by its gain A times the change in its input,



Figure 1.5 A dc model of the output stage in Fig.2.10.

$$V_{gs1} = -V_t - V_{OV} + A[V_O - (V_i - V_{OSP})]$$
(1.8)

$$V_{gs2} = V_t + V_{OV} + A[V_O - (V_i - V_{OSN})]$$
(1.9)

$$I_{d1} = -\frac{k_{p}}{2} \left(\frac{W}{L}\right)_{1} (V_{gs1} - V_{tp})^{2} = -\frac{k}{2} \frac{W}{L} (V_{gs1} + V_{t})^{2}$$
(1.10)

$$I_{d2} = \frac{k'_n}{2} \left(\frac{W}{L}\right)_2 (V_{gs2} - V_m)^2 = \frac{k'}{2} \frac{W}{L} (V_{gs2} + V_t)^2$$
(1.11)

Also, $I_o = \frac{V_o}{R_L}$. From KCL at the output, $I_{d1} + I_{d2} + I_o = 0$, and we can get

$$V_{O} = \frac{V_{i} - \frac{V_{OSP} + V_{OSN}}{2}}{1 + \frac{1}{k' \frac{W}{L} A[2V_{OV} - A(V_{OSP} - V_{OSN})]R_{L}}}$$
(1.12)

If
$$V_{OSP} = V_{OSN} = 0$$
,
 $V_O = \frac{V_i}{1 + \frac{1}{k' \frac{W}{L} A2V_{OV}R_L}} = \frac{V_i}{1 + \frac{1}{2Ag_m R_L}} \cong V_i \left(1 - \frac{1}{2Ag_m R_L}\right)$ (1.13)

If $A(V_{OSP} - V_{OSN}) \ll 2V_{OV}$ and $2Ag_m R_L >> 1$,

$$V_{O} = \frac{V_{i} - \frac{V_{OSP} + V_{OSN}}{2}}{1 + \frac{1}{k' \frac{W}{L} A2V_{OV}R_{L}}} = \frac{V_{i} - \frac{V_{OSP} + V_{OSN}}{2}}{1 + \frac{1}{2Ag_{m}R_{L}}} \cong V_{i} - \frac{V_{OSP} + V_{OSN}}{2}$$
(1.14)

Therefore, the input offset voltage of the buffer is approximately $-(V_{OSP} + V_{OSN})/2$

Although quasi-complementary circuits reduce its output impedance and improve the output swing, they suffer from two problems. First, these circuits present difficult design problems in frequency compensation. Second, if an offset occurs between error amplifier EP and EN, the current balance between the output drivers M_1 and M_2 no longer exists and the current flow through these devices is therefore uncontrolled. From a design standpoint, the

quiescent current is chosen to be barely high enough to limit crossover distortion to an acceptable level. Although further increases in the quiescent current reduce the crossover distortion, they also worsen the problem of power dissipation. Therefore, a well-defines quiescent current with nonzero offset is a key design constraint.

One way to control the quiescent current is to sense and feedback a copy of the current [3]. Fig. 1.6 shows the simplified schematic of the circuit [4]. The feedback circuit of the two error amplifiers tries to insure that the voltages in the loop sum to be zero. M_9-M_{12} altogether contribute to current sensing. When V_{OS} is positive, M_6 tries to turn off and so does M_{6A} . I_{M9} reduces thus reducing I_{M12} . A reduction in IM12 reduces I_{M8A} , thus decreases V_{GS8A} . Ideally V_{GS8A} decreases by an amount equal to V_{OS} . A similar result holds for negative offsets and offsets in the error amplifier A2. With careful design, this circuit could control the quiescent current by correcting offset voltage in the error amplifier. However, the minimum output voltage will be limited by diode connecting of M_8 , and

 $V_{OUT(\min)} = V_{SS} + V_{OV17} + V_{GS8}$ (1.15)



Figure 1.6 Class AB output stage with offset correction circuit [4].

Another way to limit the quiescent current variations is to design the error amplifier to have low gain [5] [6]. The quiescent current is controlled by the gate-source voltages on the power transistors, which in turn are controlled by the outputs of the error amplifiers. Therefore, reducing the error-amplifier gain reduces the gate-source voltage variations and the quiescent current for a given variation in the offset voltage.

To study this situation quantitatively [7], define the quiescent current in the output devices as the common-mode component of the current flowing from V_{DD} to $-V_{SS}$ with V_i=0, Then $I_Q = \frac{I_{D2} - I_{D1}}{2}$. Substituting (1.8)-(1.11) into above equation gives

$$I_{Q} = \frac{k'}{4} \frac{W}{L} \left((V_{OV} + A[V_{O} + V_{OSN}])^{2} + (-V_{OV} + A[V_{O} + V_{OSP}]^{2} \right)$$
(1.16)

Since $V_O = 0$ if $V_{OSP} = V_{OSN} = 0$, (1.16) shows that

$$I_{Q}\Big|_{VOSP=0}^{VOSP=0} = \frac{k}{4} \frac{W}{L} \left((V_{OV})^{2} + (-V_{OV})^{2} \right) = \frac{k}{2} \frac{W}{L} (V_{OV})^{2}$$
(1.17)

From, (1.14) with V_i=0,

$$V_o + V_{OSP} \cong \frac{V_{OSP} - V_{OSN}}{2}$$
(1.18)

$$V_o + V_{OSN} \cong -\frac{V_{OSP} - V_{OSN}}{2} \tag{1.19}$$

Substituting (1.18) and (1.19) into (1.16) gives

$$I_{Q} = \frac{k'}{2} \frac{W}{L} \left(V_{OV} - A \left[\frac{V_{OSP} - V_{OSN}}{2} \right] \right)^{2}$$
(1.20)

Define ΔI_Q as the change in I_Q caused by nonzero offsets; that is,

$$\Delta I_{\mathcal{Q}} = I_{\mathcal{Q}} \Big|_{\substack{\text{VOSP}=0\\\text{VOSN}=0}} - I_{\mathcal{Q}}$$
(1.21)

Substituting (1.20) and (1.17) into (1.21) gives

$$\Delta I_{Q} = \frac{k}{2} \frac{W}{L} A \left(V_{OSP} - V_{OSN} \right) \left[V_{OV} - A \left(\frac{V_{OSP} - V_{OSN}}{4} \right) \right]$$
(1.22)

To evaluate the magnitude of ΔI_Q , we will compare it to the quiescent current with zero

offsets by dividing (1.22) by (1.17). The result is

$$\frac{\Delta I_{Q}}{I_{Q}\Big|_{VOSP=0}} = A\left(\frac{V_{OSP} - V_{OSN}}{V_{OV}}\right) \left[1 - A\left(\frac{V_{OSP} - V_{OSN}}{4V_{OV}}\right)\right]$$
(1.23)

If $A(V_{OSP} - V_{OSN}) << 4V_{OV}$,

$$\frac{\Delta I_{Q}}{I_{Q}\Big|_{VOSP=0}^{VOSP=0}} \cong A\left(\frac{V_{OSP} - V_{OSN}}{V_{OV}}\right)$$
(1.24)

Therefore, to keep the fractional change in the quiescent current less than a given amount, the maximum error-amplifier gain is

$$A < \left(\frac{V_{OV}}{V_{OSP} - V_{OSN}}\right) \left(\frac{\Delta I_Q}{I_Q \Big|_{VOSP=0}^{VOSP=0}}\right)$$
(1.25)

For example, if $V_{ov} = 200 \text{mV}$, $V_{osp} - V_{osN} \approx 5 \text{mV}$, and up to 20 percent variation in quiescent current is allowed, (1.25) shows that the error amplifier gain should be less than about 8 [5] [6].





Figure 1.7 Schematic of the error amplifier EP and power transistor M1 in Fig.1.5

Fig.1.7 shows the schematic of the error amplifier EP and M_1 from Fig. 1.5 [6]. A complementary structure used to drive M_2 is not shown. The difference between V_i and V_o is sensed by the differential pair M_{11} and M_{12} , which is biased by the tail current source I_{BB} . The load of the differential pair consists of two parts: source-follower transistors M_{13} and M_{14} and current mirror M_{15} and M_{16} . It can be considered a general one-stage CMOS amplifier consisted of transistors M_{11} , M_{12} , M_{15} and M_{16} , and the purpose of the source-follower transistors is to reduce the output impedance of the error amplifier EP to set its gain to a well-defined low value. The gates of the source-follower transistors are biased by a negative feedback loop including M_{15} , M_{17} , I_{SS} , and M_{13} . This circuit adjusts the voltage at the gate of M_{13} so that M_{17} operates in the active region and conducts I_{SS} .

Since M₁₅ and M₁₇ form a current mirror, and so do M₁₅ and M₁₆ with (W/L)₁₅=(W/L)₁₆

$$|I_{D15}| = |I_{D16}| = |I_{D17}| \frac{(W/L)_{15}}{(W/L)_{17}} = |I_{SS}| \frac{(W/L)_{15}}{(W/L)_{17}}$$
(1.26)
With $V_i = V_o$, $I_{D11} = I_{D12} = I_{BB}/2$. From KCL,

$$|I_{D14}| = |I_{D16}| - |I_{D11}| = |I_{SS}| \frac{(W/L)_{15}}{(W/L)_{17}} - \frac{|I_{BB}|}{2}$$
(1.27)

Since $I_{D13} = I_{D14}$ when $I_{D11} = I_{D12}$, $V_{SD16} = V_{SD15} = V_{SG15} = V_{SG1}$ Therefore, ignoring channel-length modulation,

 $|I_{D1}| = |I_{D15}| \frac{(W/L)_1}{(W/L)_{15}} = |I_{SS}| \frac{(W/L)_1}{(W/L)_{17}}$ (1.28)

This equation shows that the drain current in M₁ is controlled by I_{ss} and a ratio of transistor sizes if the offset voltage of the error amplifier EP is zero so that $V_o = 0$ when $V_i = 0$. In practice, $(W/L)_1 >> (W/L)_{17}$ so that little power is dissipated in the bias circuits.

Another design consideration therefore comes out from these equations. To keep the gain of the error amplifier low under all conditions, M_{14} must never cut off. Therefore, from (1.27), $|I_{D16}|$ should be greater than the maximum value of I_{D11} . Since the maximum value of I_{D11} is I_{BB} , gives

$$\left|I_{D16}\right| = \left|I_{SS}\right| \frac{(W/L)_{15}}{(W/L)_{17}} > I_{BB}$$
(1.29)

Consider the entire small signal current from the differential pair flows at the error-amplifier output and the transconfuctance is $G_m = g_{m11} = g_{m12}$, The output resistance of the error amplifier is dominated by source-follower transistor M_{14} . $R_o = \frac{1}{g_{m14} + g_{mb14}}$ Therefore, the gain of the error amplifier EP is

$$A = G_m R_o = \frac{g_{m11}}{g_{m14} + g_{mb14}}$$
(1.30)

A drawback of this error amplifier is that the output swing is limited. Review Fig. 1.7. We want a large swing at node A, the gate of M_1 , to provide a strong gate drive for M_1 . However, the maximum voltage of node A is limited by

$$(V_i - V_{GS11} + V_{OV11}) \tag{1.31}$$

Form (1.31), the maximum source-gate voltage of M_1 is

$$V_{DD} - (V_i - V_{GS11} + V_{OV11})$$
(1.32)

With good linearity desired, V_o should precisely follow V_i . When driving a low impedance load, output current increases as both V_i and V_o rise. (1.32) shows that the higher V_i the smaller capable source-gate voltage of M₁, which means we need a larger-sized M₁ to achieve the desired output current.

Compared with Fig.1.7, Fig.1.8 shows an alternative error amplifier [7], which has a better output swing. A complementary structure used to drive M₁ is not shown. In the balanced quiescent condition, the drain currents of transistors M₁₅ and M₁₆ are equal to half the bias current I_{BB}. Because the sizes of transistors M₁₀ and M₁₁ are the same as those of transistors M₁₂ and M₁₃, respectively, and the drain currents of these four transistors are the same, the drain voltage of transistor M13 is the same as the gate voltage if the channel length modulation is ignored. Thus the drain current of the output transistor M₂, the quiescent current, is given by $I_{D2} = I_{D13} \frac{(W/L)_2}{(W/L)_{12}}$ (1.33)



Figure 1.8 An alternative error amplifier in Fig. 1.5

The drain current I_{D13} of M_{13} is $I_{D13} = I_{D3} \frac{(W/L)_{13}}{(W/L)_3}$ (1.34) Since the drain current of M_3 is equal to half of the bias current I_{BB}, we can drive the output current by combining (1.33) and (1.34), which is given by

$$I_{D2} = \frac{1}{2} \frac{(W/L)_2}{(W/L)_3} I_{BB}$$
(1.35)

(1.35) shows that the quiescent current of M₂ is linearly related to the bias current I_{BB} and the W/L ratio of the two transistors M₃ and M₂. If we want to decrease the quiescent current without sacrificing the current drive capability, we can make M13 larger. If we increase the size of M13 by a factor of K, the gate over-drive of M₂, $V_{GS2} - V_{t2}$, is given by

$$V_{GS2} - V_{t2} = V_{GS10} + V_{GS11} - V_{GS12} - V_{t2}$$

= $\sqrt{\frac{2(W_{11}/W_3)(I_{BB}/2)}{\mu C_{OX}(W_{10}/L_{10})}} (1 - \sqrt{K}) + \sqrt{\frac{2(W_{11}/W_3)(I_{BB}/2)}{\mu C_{OX}(W_{11}/L_{11})}} + (V_{t10} - V_{t12})$ (1.36)

assuming $W_{12} = W_{10}$, $W_4 = W_3$, $W_6 = W_{11}$, and $L_{12} = L_{10}$. (1.36) shows that increasing the ratio of K minimizes the overdrive voltage, and therefore decreases the quiescent current. However, increasing the ratio of K will deteriorate the linearity. It needs to be traded off carefully.

There is another disadvantage worth noticing here in this circuit. Consider channel length modulation effect, that $V_{DS8} \neq V_{DS9}$, and $V_{GS10} = V_{DS10} \neq V_{DS12}$ will result in the difference of current, say, $I_{M9} \neq I_{M8}$ and $I_{M9} \neq I_{M12}$. The difference increases with the supply voltage, which again causes an unwanted offset in quiescent current.

(4) Combined Common-Drain Common-Source Configuration

The gain of error amplifiers, as discussed in the previous section, is limited to establish adequate control on the output current. Its bandwidth is usually limited, too, to avoid stability problems. These two limitations make a common-source configuration suffer from an increase in harmonic distortion, especially at high frequencies.

An alternative to overcome this problem is to use a combination of the common-drain and common-source configurations as shown in Fig. 1.9 [8] [9]. The key aspect of this circuit is that it uses two buffers connected to the output: The transistors M_{11} - M_{-12} and error amplifiers EP, EN with offset voltage V_{OS} can be considered a Class-B quasi-complementary buffer. It works only when the output swing is large, but turns off with a zero or small output. Another Class-AB common-drain buffer is consisted of M_1 - M_4 , which controls the quiescent output current and improves the frequency response as we shall discuss later. V_{OS} can be introduced by intentionally mismatching the input differential pair in each error amplifier. The circuit can be designed so that, when $V_0 = V_1 = 0$, the introduction of V_{OS} turns off M11 and M12. Error amplifiers, EP and EN, both can have a high gain, which decreases the harmonic distortion, and they are often designed as onstage amplifiers with the gain $\approx g_m r_0$.

The output swing is dominated by a common-drain buffer. Consider the V_1 voltage range which is limited by the diode connected M_3 and M_4 . Then,

$$V_o(\max) \approx V_1(\max) = V_{DD} - |V_{OV5}| - V_{gs3}$$
 (1.37)

By adding one extra branch as show in Fig.1.10, this limitation can be overcome. The new branch consisted of transistors M_7 and M_8 operates in parallel with the branch containing M_3 to M_6 to produce V_1 . The swing of V1 in Fig.1.9 is limited by the threshold voltages of M3 and M4 as discussed earlier. In contrast, the new branch in Fig.1.10 can drive V_1 within an overdrive of either supply while M_7 and M_8 operate in the active region. Improving the swing of V_1 also improves the output swing.

Consider the frequency response of the circuit shown in Fig.1.7 qualitatively. The circuit has two paths from V_1 to output. The path through the common-source transistors M_{11} and M_{12} may be slow because of the need to limit the bandwidth of the error amplifiers to guarantee stability of the circuit. On the other hand, the path through the common-drain transistors M_1 and M_2 is fast because source followers are high-bandwidth circuits. Since currents from the two output buffers are added up, the fast path will dominate for high-frequency signals and it simplifies the design required to guarantee stability.

There is also a notable drawback of this circuit, that is, to use large-sized transistors to achieve a desired output swing. In addition to the huge-sized power transistors M_{11} and M_{12} , M_1 - M_4 have to be relatively large enough to get an appropriate threshold voltage under their bias condition. The size of M_2 and M_4 is about half of M_{11} and so are the n-channel transistors, M_1 , M_3 and M_{12} . [9]

Figure 1.9 Combined common-drain, common source output stage.





Figure 1.10 Combined common-drain, common source output stage with high swing.

(5) Parallel Common-Source Configuration

Fig.1.11 shows another circuit with similarities discussed in previous section [10]. This circuit combines two buffers in parallel at the output. The error amplifiers EP_1 and EN_1 with M_1 and M_2 form the first buffer, which controls the operation of the output stage with Vi=0. The error amplifiers EP_2 and EN_2 with M_{11} and M_{12} form the second buffer, which dominates the operation of the output stage for large-magnitude output voltages.



Figure 1.11 Parallel common-source configuration of output stage

This behavior stems from small offset voltages intentionally built into the amplifiers EP₁ and EN₁. With EP₂ and EN₂ properly adjusted to have high gain, and EP₁ and EN₁ to have low gain, these offsets have little effect on the drain currents of M₁ and M₂. Therefore, M₁ and M₂ operate in the active region when Vi=0, and the first buffer operates in Class-AB mode. On the other hand, the product $V_{OS}A_{EP1}A_{EP2}$ and $V_{OS}A_{EN1}A_{EN2}$ are conditioned by design to be big enough to force V_{gs11} >V_{t11} and V_{gs12} < V_{t12} so that M11 and M12 are off when V_i=0. The second buffer operates in Class-B mode to avoid higher quiescent current introduced by power transistors M₁₁ and M₁₂.

In general, more amplifiers contribute to more poles and zeros in the frequency domain. This should be taken into serious consideration to avoid stability problems when designing each amplifier in Fig.1.11. Fig.1.12 and Fig.1.13 show the schematics of EP₁ and EP₂, respectively. Further detail frequency response analysis shall be left aside here.

Now consider the effect of the offset voltage, V_{os}, which is introduced by making $(W/L)_3 \cong 0.8(W/L)_4$ [10]. Assume that $V_0 = 0$ when $V_i = 0$. Increasing V_{os} reduces I_{D3} because of $I_{D3} = I_{B1} \frac{(W/L)_3}{(W/L)_3 + (W/L)_4}$. (1.38)

Since, $I_{D3} = |I_{D5}| + I_{B2}$, and $I_{D1} = (I_{D3} - I_{B2}) \frac{(W/L)_1}{(W/L)_5}$ (1.39)



Figure 1.12 The error amplifier EP₁ shown in Fig.1.11



Figure 1.13 The error amplifier EP₂ shown in Fig.1.11

 I_{D3} must be greater than I_{B2} to prevent M₅ from cutoff and avoid losing control over the quiescent current. Therefore, the offset must be chosen small enough so that $|I_{D5}| > 0$. In practice, however, there are some mismatches of the error amplifiers caused by unexpected random effects. Since we intend to bias M₁₁ in cutoff region, the random components must not be larger than the systematic offset in magnitude and opposite in polarity. Therefore, V_{OS} is chosen to be bigger than the expected random offsets.

Consider the transfer characteristic of this circuit. When |Vi| is small, and M_{11} and M_{12} are not turned on, the output is

$$V_{O} = \frac{V_{i}}{1 + 1/(A_{EP1}g_{m1}R_{L}/2 + A_{EN1}g_{m2}R_{L}/2)}$$
(1.40)

When V_i is large, M_{11} can be turned on, and the output becomes

$$V_o \approx V_i - V_{os} \tag{1.41}$$

if $A_{EP2} \rightarrow \infty$.

To determine the range of input voltages for which M_{11} and M_{12} are both off, assume that the gains A_{EP1} and A_{EP2} are constant.,

$$V_3 = [V_O - (V_i - V_{OS})]A_{EP1}A_{EP2} + V_K$$
(1.42)

where *K* is a constant. When $V_{2+} = V_2$ at EP₂, gives

$$V_3 = V_K = V_{gs25} = V_{OV25} + V_{t25} + V_{SS}$$
(1.43)

Then, define $V_{i(\min)}$ as the minimum input to turn on M_{11} . Let $V_3 = V_{DD} - |V_{tp11}|$, substituting (1.42) with (1.43) into (1.40) gives

$$Vi(\min) = V_{OS} \left(1 + A_{EP1} g_{m1} R_L\right) - \frac{\left(V_{DD} - V_K - \left|V_{tp11}\right|\right) \left(1 + A_{EP1} g_{m1} R_L\right)}{A_{EP1} A_{EP2}}$$
(1.44)

If $A_{EP2} \rightarrow \infty$, gives

$$Vi(\min) = V_{OS} (1 + A_{EP1} g_{m1} R_L)$$
(1.45)

The derivative analysis shows that M_{11} and M_{12} remain off for only a small range of input voltages. Therefore, the nonlinearity introduced by turning on M_{11} or M_{12} occurs when $|V_i|$ is small. As a result, this circuit is suitable for ISDN (Integrated Service Digital Network) line-driving application for which it was designed because the required four-level output code does not include zero, avoiding distortion that would be introduced by turning M_{11} and M_{12} on or off [10] if a zero-level output pulse were required.

Similar to Fig.1.10, this parallel common-source configuration with two sets of buffers will need a larger chip area. When an output stage is designed with a large current drive and a smaller impedance of the output load, bigger-sized output power transistors will be needed. When applying this kind of circuit to an audio amplifier, it should be seriously considered that transistors M_1 and M_2 will take up a large chip area as another set of power transistors, M_{11} and M_{12} .

The drawbacks of different output stages introduced in Sec. 1.1.1. are summarized in Table 1-2. Among these different output stages, Common-Drain and Common Source configurations in particular are apparently not suitable to be used in audio amplifiers. Counterparts such as Combined Common-Drain Common-Source and Parallel Common Source configurations are uneconomical in size for consuming larger chip area. On the other

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hand, while Common-Source with error amplifier configuration may seem relatively economical of size, the error amplifier in this design has to deal with the problem of quiescent current at the expense of linearity and output power performance.

Drawbacks of different Class-AB output stages			
Configuration	Ref.	Drawbacks	
Common-Drain	-	Small output swing	
Common course	-	High output impedance	
Common-source		High signal distortion	
	[3]	Output swing limited by offset cancellation circuit	
Common-source with error	[6]	Poor linearity due to error amplifier's low gain	
		The use of larger-sized power MOS due to a limited	
ampinier		output swing of the error amplifier	
	[7]	Small supply voltage range	
Combined Common-Drain	[8]	Uneconomical in size due to the use of two sets of	
Common-Source	[9]	power MOS	
Denellal Common Course	[10]	Uneconomical in size due to the use of two sets of	
ratatiet Common-Source		power MOS	

Table 1-2 Design Specifications of this work

1.2 Motivations

In view of the aforementioned disadvantages, we decide to put forth a better output stage structure by improving the Common-Source with error amplifier configuration. Compared with its counterparts in Table 1-2, the structure of Common-Source with error amplifier output stage is simpler and consequently is economical of chip size. The objective of this thesis is to design a new kind of error amplifier that ameliorates all the drawbacks listed in Table 1-2, which is economical of size, has high output power and high linearity, and works under a wider range of supply voltage.

1.3 Main result

The chip of our design is fabricated by the UMC 0.5um +/-20V2P2M high voltage process. It can works under 10V to 18V of supply voltage. With a supply voltage of 15V and an output resistor load of 8 Ω , output power will be 2W with 0.062% THD. The quiescent current of this chip is 20mA typically. The chip dimension is 2210um x 3497um with an additional test key.

1.4 Thesis organization

This thesis aims to improve the design of linear audio amplifier output stage. In Chapter 2, we will further discuss in detail the structure of Class-AB output stage proposed by this thesis. Also, we will show how the functions of mute, standby, and volume control are realized in actual circuit design. Finally, in the last part of Chapter 2, we will provide the results of pre-simulation. In chapter 3, the complete layout and results of post-simulation will be shown. Chapter 4 mainly concludes the distinguishing features and contributions of this thesis, and it also provides possible work and improvements from a future perspective.

CHAPTER 2

Architecture and circuit design

2.1 Design specification and consideration

Class-AB single-ended audio amplifier with high supply voltage and high output power is not that popular a research target in the academic arena, so we turn to search for some product specifications of several well-established semiconductor corporations for reference. These include companies such as *STMicroelectronics, TEXAS INSTRUMENTS, National Semiconductor*, and so on. They all have products with similar applications of single ended Class-AB audio amplifiers that work under a wide supply voltage range, 10V~18V. However, limited by our choices of process and packaging, we in the end choose ST-TDA7469L [11] to be the reference of our design spec., and lay down our design targets as in Table 2-1.

Symbol	Parameter	Test condition	Value	Unit
Vs	Supply voltage range		10~18	V
Iq	Total quiescent current		<50	mA
Po	Output power	>1.3	W	
THD	Total harmonic distortion	P ₀ =1W, f=1kHz	<0.4	%
BW	Unit gain bandwidth		>0.6	MHz
Ipeak	Out peak current		<1.1	А
PSRR	Power supply rejection ratio	F=1kHz	>50	dB

(Testing condition	$V_{S} = 14V \cdot R$	R = 80. Tem	p=25°C)
J	resung condition	$v_0 - 1 + v_0 + v_0$	<u> </u>	p-20

2.2 Full circuit architecture

Fig.2.1 shows the block diagram of this chip [11]. The stereo audio channel consists of two buffered amplifiers, OP_{1A} and OP_{1B} , and two volume control amplifiers, VC_A and VC_B . Another open loop buffered amplifier, OP_{1C} , is just for testing. The two unit gain buffers, OP_{2A} and OP_{2B} , are to be used as earphone output, and their structures are the same as OP_{1A} and OP_{1B} , respectively, but differently sizing. Both of the two volume control amplifiers are controlled by a simple analog to digital converter, A_D. The mute control circuit is also contained in A_D. The function block, BIAS, including the standby control function, produces all needed current sources for each circuit.

We define the output reference voltage as $V_{REF} = \frac{V_{DD} - V_{SS}}{2}$. The 8 Ohm load resistance will connect the output and V_{REF} through a capacitor outside the chip. V_{REF} is also taken as the common mode voltage in the close loop buffered amplifier. The unit gain amplifier, OP_{VREF} , is used to drive the reference voltage, V_{REF} .



Figure 2.1 The block diagram of this chip

2.3 Buffered amplifier

Table 2-1 lists the required design targets. The design constraints include a highly supply voltage ranging from 10V to 18V, and an impedance load as low as 8 Ohm. Our design target is to achieve < 0.4% THD, and control the system's quiescent current as low as 50mA. In section 1.1.1, we introduced a lot of architecture and circuits of Class-AB output buffers. Some of them ([6] [8] [9]) may take up too much chip area to be used in high-power output applications, and some [7] may not be suitable for a high supply voltage range (10V~18V) to maintain stable linearity and acceptable quiescent current. Also, two other attractive structures can be referred to as in [12] [13]. However, to meet the high-power output requirement, these simple structures have big problems to compromise between current consumption, linearity and chip area.



Figure 2.2 The block diagram of buffered amplifier

2.3.1 Architecture of buffered amplifier

We as a result propose a new set of error amplifiers which form the common-source configuration output stage with the function of short circuit protection. Besides, we use a two-stage amplifier as the pre-amplifier to get a high gain in the gain stage. These two parts form a buffered amplifier as show in Fig.2.2.

2.3.2 Error amplifier for output buffer

Fig.2.3 shows a schematic of the error amplifier EP and M_1 from Fig.2.2. A complementary structure used to drive M_2 is shown in Fig.2.4. For convenience, we take EP as the example for the following discussion. The error amplifier EP shown in Fig.2.3 can be recognized as an OTA by ignoring transistors M_{P10B} , M_{P11B} , M_{P13} , and M_{P14} . This OTA could provide a high output swing to drive the power transistor M_1 . The difference between V_{in2} and V_{EP_OUT} is sensed by the differential pair M_{P1} and M_{P2} , which is biased by the tail current source I_{BP} with a current mirror. The load of the differential pair consists of a chain of current mirror branches used to define the quiescent current. Applying similar ideas derived from the circuit shown in Fig.1.7, the source-follower transistors M_{P13} and M_{P14} will reduce the output impedance of the error amplifier EP to set its gain to a well-defined low value. The gates of source-follower transistors are biased by a negative feedback loop including M_{P11} , M_{P11B} , M_{P10B} , M_{P10B} , and M_{P13} . Here the constant current source I_{SS} as shown in Fig.1.7, is replaced by a variable current mirror source, M_{P10B} , which will change its drain current as the input differential pair senses any difference.



Figure 2.3 Schematic of the error amplifier EP



MOS	MBP	MP0	MP1	MP2	MP3	MP4	MP5	MP6	
W/L(µm)	10/4	10/4	45/5	45/5	10/4	10/4	10/4	10/4	
М	1	40	20	20	4	4	4	4	
MOS	MP7	MP8	MP9	MP10	MP11	MP12	MP13	MP14	
W/L(µm)	5/4	5/4	5/4	5/4	50/4	50/4	10/4	10/4	
М	2	2	2	2	36	36	4	4	
MOS	M1	MP11B	MP10B	MC1	MC2	MC3	MC4	MC5	
W/L(µm)	106/3	50/4	5/4	10/4	10/4	10/4	10/4	10/4	
М	198	36	4	1	1	1	1	1	
MOS	MC6	MC7	MC8						
W/L(µm)	5/4	5/4	10/4	IBP=10uA					
М	1	1	1						

 Table 2-2 Transistors W/L ratio of Fig.2.3



Figure 2.4 Schematic of the error amplifier EN



MOS	MBN	MN0	MN1	MN2	MN3	MN4	MN5	MN6		
W/L(µm)	25/4	25/4	50/5	50/5	10/4	10/4	10/4	10/4		
М	1	20	24	24	4	4	4	4		
MOS	MN7	MN8	MN9	MN10	MN11	MN12	MP13	MP14		
W/L(µm)	5/4	5/4	5/4	5/4	50/4	50/4	9/4	9/4		
М	2	2	2	2	20	20	2	2		
MOS	M2	MN11B	MN10B	MC1	MC2	MC3	MC4	MC5		
W/L(µm)	66/2.5	50/4	5/4	5/2.5	5/2.5	5/2.5	5/2.5	5/2.5		
М	182	20	4	1	1	1	1	1		
MOS	MC6	MC7	MC8							
W/L(µm)	5/3	5/3	5/3	IBN=10uA						
Μ	1	1	1							

Table 2-3 Transistors W/L ratio of Fig.2.4

To further analyze this newly proposed circuit, let us begin with the quiescent condition.

Setting all the transistors symmetrical, $(W/L)_1=(W/L)_2$, $(W/L)_3=(W/L)_4$, $(W/L)_5=(W/L)_6$,

 $(W/L)_7 = (W/L)_8$, $(W/L)_9 = (W/L)_{10}$, $(W/L)_{11} = (W/L)_{12}$, and $(W/L)_{13} = (W/L)_{14}$, the tail current $I_{P0} = I_{BP} \frac{(W/L)_{P0}}{(W/L)_{BP}}$ will be equally distributed into M_{P1} and M_{P2}. Ignoring channel length

modulation,

$$I_{P5} = I_{P6} = I_{P7} = I_{P8} = \frac{I_{BP}}{2} \frac{(W/L)_{P0}}{(W/L)_{BP}} \frac{(W/L)_{P5}}{(W/L)_{P3}}$$
(2.1)

$$I_{P9} = I_{P10} = \frac{I_{BP}}{2} \frac{(W/L)_{P0}}{(W/L)_{BP}} \frac{(W/L)_{P5}}{(W/L)_{P3}} \frac{(W/L)_{P9}}{(W/L)_{P7}}$$
(2.2)

Setting $(W/L)_{10B}=2(W/L)_{10}$, gives

$$I_{P10B} \cong 2I_{P10} \tag{2.3}$$

Setting $(W/L)_{11}=(W/L)_{11B}$, gives

$$I_{P11} \cong I_{P11B} = I_{P10B} \cong 2I_{P10} = 2I_{P9}$$
(2.4)

Since $|I_{P11}| = |I_{P13}| + I_{P9}$,

$$I_{P13} = |I_{P11}| - I_{P9}^{BB} \cong 2I_{P9} - I_{P9} = I_{P9}$$
(2.5)

Therefore, the quiescent current of the output buffer is well-defined as

$$I_{quiescent} \approx I_1 = 2I_{P10} \frac{(W/L)_1}{(W/L)_{P11}} = I_{BP} \frac{(W/L)_{P0}}{(W/L)_{BP}} \frac{(W/L)_{P5}}{(W/L)_{P3}} \frac{(W/L)_{P9}}{(W/L)_{P7}} \frac{(W/L)_1}{(W/L)_{P11}}$$
(2.6)

This equation shows that the drain current in M_1 is controlled by I_{BP} and the (W/L) ratio of transistors, if the offset voltage of the error amplifier EP is zero, $V_o = 0$ when $V_i = 0$. To find the gain of the error amplifier in the quiescent condition, we assume that the input differential voltage is small enough so that M_{P10B} can be regarded as a constant current source. Considering the entire small signal current from the differential pair flows at the error-amplifier output, EP OUT, the transconductance is

$$G_{m} = \frac{g_{mP1}}{2} \frac{1}{g_{mP3}} g_{mP5} \frac{1}{g_{mP7}} g_{mP9} + \frac{g_{mP2}}{2} \frac{1}{g_{mP4}} g_{mP6} \frac{1}{g_{mP8}} g_{mP10} \left(\frac{1}{g_{mP12}} / / \frac{1}{g_{mP14}}\right) g_{mP11}.$$
 (2.7)

In the quiescent condition, $g_{mP1} = g_{mP2}$, $g_{mP3} = g_{mP4}$, $g_{mP5} = g_{mP6}$, $g_{mP7} = g_{mP8}$, $g_{mP9} = g_{mP10}$, $g_{mP11} = g_{mP12}$, $g_{mP13} = g_{mP14}$, and $g_{mP12} \gg g_{mP14}$ because $I_{P12} \cong 2I_{P14}$, and the W/L ratio of M_{P12} is usually much lager than M_{P14} so as to reduce the quiescent current. Therefore, we can simplify (2.7) as

$$G_m = g_{mP1} \frac{1}{g_{mP3}} g_{mP5} \frac{1}{g_{mP7}} g_{mP9}$$
(2.8)

The output resistance of the error amplifier is dominated by the source-follower transistor

M_{P13}, and
$$R_o = \frac{1}{g_{mP13} + g_{mb P13}} = \frac{1}{g_{mP13}(1+\eta)}$$
 (2.9)

The coefficient $\eta = \frac{g_{mb\ P13}}{g_{mP13}}$, and $A_{EP} = G_m R_o = g_{mP1} \frac{1}{g_{mP3}} g_{mP5} \frac{1}{g_{mP7}} g_{mP9} \frac{1}{g_{mP13}(1+\eta)}$ (2.10)

Since $g_m = \sqrt{2k'(W/L)I_d}$, and $I_{P1} = I_{P3}$, $I_{P5} = I_{P7}$, $I_{P9} = I_{P13}$. (2.10) can be re-written as

$$A_{EP} = \sqrt{\frac{(W/L)_{P1}}{(W/L)_{P3}}} \frac{(W/L)_{P5}}{(W/L)_{P7}} \frac{(W/L)_{P9}}{(W/L)_{P13}} \frac{1}{(1+\eta)}$$
(2.11)

The above equation shows that the gain of the error amplifier is well-defined by the W/L ratio of transistors with appropriate bias. In practice, the drain current of M_{P10B} will vary with the input differential voltage, $V_d = (V_{in1} - V_{in2})$. If V_d is negative, M_{P1} will conduct more tail current than M_{P2} . As the difference increases, so does I_{P9} , too, but I_{P11} decreases. When $I_{P9} = I_{P11}$, M_{P13} will be cutoff, and the output impedance of the error amplifier is no longer dominated by the source-follower transistor, M_{P13} . The output impedance of the error amplifier $R_o \approx (r_{o P9} // r_{o P11})$, and voltage gain will highly increase to the order about an $g_m r_o$. This results in an additional benefit. The higher gain of the amplifiers enhances the linearity of output buffer under higher output power operation.

Consider the boundary condition of the above situation. This happens at $I_{P1} = 2I_{P2}$, and

$$I_{P1} = \frac{1}{2}k'(W/L)_{P1}(V_{in} + \frac{V_d}{2} - V_t)^2 = \frac{2}{3}I_{P0} = \frac{2}{3}\frac{(W/L)_{P0}}{(W/L)_{BP}}I_{BP}$$
(2.12)

$$I_{P2} = \frac{1}{2}k'(W/L)_{P2}(V_{in} - \frac{V_d}{2} - V_t)^2 = \frac{1}{3}I_{P0} = \frac{1}{3}\frac{(W/L)_{P0}}{(W/L)_{BP}}I_{BP}$$
(2.13)

From (2.12), and (2.13), the threshold input differential voltage, which cuts off the transistor M_{P13} , is

$$V_{d} = \sqrt{\frac{I_{BP}}{3k'(W/L)_{P1}} \frac{(W/L)_{P0}}{(W/L)_{BP}}} \left(2 - \sqrt{2}\right)$$
(2.14)

However, in practice, there are always some mismatches of the error amplifiers caused by unexpected random effects. If the random offset voltage, V_{OS} , is higher than V_d shown in (2.14), the gain of the error amplifier will increase considerably, and the quiescent current will be out of control. Therefore, V_d is chosen to be bigger than the expected random offset voltage.

In section 1.1.1, (1.24) shows how to estimate the possible variation of the quiescent current at a given offset voltage. This equation, however, should be modified since the gain of the error amplifier shown in Fig.2.2 will be changed with V_{OS} increasing. Now, define A_{OS} as the changed gain of both two error amplifiers, EP and EN, when V_{OSP} and V_{OSN} exist as shown in Fig.1.5. The equation (1.24) becomes

$$\frac{\Delta I_{Q}}{I_{Q}\Big|_{\substack{VOSP=0\\VOSN=0}}} \cong A_{OS}\left(\frac{V_{OSP} - V_{OSN}}{V_{OV,M1}}\right)$$
(2.15)

The A_{OS} represents the gain of error amplifiers, EP and EN, affected by V_{OSP} . Review (2.10), the ratio, $\frac{g_{mP1}}{g_{mp3}}$ and $\frac{g_{mP5}}{g_{mp7}}$, will not be affected by V_{OSP} , but $\frac{g_{mP9}}{g_{mp13}}$ will. Therefore, $\frac{(A_{EP})_{OS}}{A_{OS}|_{VOSP=0}} \approx \frac{(g_{mP9})_{OS}}{g_{mP9}} \frac{g_{mP13}}{(g_{mP13})_{OS}} = \sqrt{\left(1 + \frac{\Delta I_{d9}}{I_{d9}}\right)\left(\frac{1}{1 - \Delta I_{d13}/I_{d13}}\right)}$ (2.16)

Considering how V_{OSP} affects the input differential pair;

$$\left|\frac{\Delta I_{P1}}{I_{P1}}\right| = \left|\frac{\Delta I_{P2}}{I_{P2}}\right| = \frac{\left(V_{OV P1} + \frac{V_{OSP}}{2}\right)V_{OSP}}{V_{OV P1}^2}$$
(2.17)

Assuming
$$V_{OV,MP1} >> V_{OSP}/2$$
, $\left|\frac{\Delta I_{P1}}{I_{P1}}\right| = \left|\frac{\Delta I_{P2}}{I_{P2}}\right| = \frac{V_{OSP}}{2V_{OV,MP1}}$ (2.18)

Applying similar reasoning to (2.2), and (2.5),

$$\frac{\Delta I_{d9}}{I_{d9}} = \frac{V_{OSP}}{2V_{OV,MP1}} \frac{(W/L)_{P5}}{(W/L)_{P3}} \frac{(W/L)_{P9}}{(W/L)_{P7}}$$
(2.19)

$$\frac{\Delta I_{d13}}{I_{d13}} = 2\frac{\Delta I_{d9}}{I_{d9}} = \frac{V_{OSP}}{V_{OV,MP1}} \frac{(W/L)_{P5}}{(W/L)_{P3}} \frac{(W/L)_{P9}}{(W/L)_{P7}}$$
(2.20)

Substituting (2.19) and (2.20) with (2.16) and rearranging properly,

$$\frac{(A_{EP})_{OS}}{A_{OS}|_{VOSP=0}} = \sqrt{\frac{2V_{OV,MP1} + V_{OSP} \frac{(W/L)_{P5}}{(W/L)_{P3}} \frac{(W/L)_{P9}}{(W/L)_{P7}}}{2V_{OV,MP1} - 2V_{OSP} \frac{(W/L)_{P5}}{(W/L)_{P3}} \frac{(W/L)_{P9}}{(W/L)_{P7}}}}$$
(2.21)

The above equation shows an important result. To minimize the variation of A_{os} affected by V_{OS}, the W/L ratio of $\frac{(W/L)_{P5}}{(W/L)_{P3}} \frac{(W/L)_{P9}}{(W/L)_{P7}}$ must not be too big.

2.3.3 Short circuit protection

Consider the block diagram shown in Fig.2.2 without short circuit protection function. If we accidentally connect the output to V_{SS} or V_{DD} , or operate the chip improperly, M1 or M2 will be damaged or the whole system will be overheated because of the unexpectedly large output current caused by a short-circuited output.

Fig.2.5 shows the schematic of a short circuit protection function for the power transistor M_1 . A complementary structure used to protect M_2 is shown in Fig.2.6. Consider the transistors $M_{EP1} \sim M_{EP5}$, which form an one-stage error amplifier, ESP, used to sense output current. By connecting ESP, M_{SP1} , M_{SP5} and M_{SP2} as a feedback loop, the differential inputs of ESP, OUT and V_{SEN_P} can be regarded as virtually short-circuited. Thus the drain current of M_1 can be sensed accurately by M_{SP1} with a ratio of $\frac{(W/L)_{MSP1}}{(W/L)_{M1}}$. M_{SP5} and M_{SP2} form a current mirror so that I_{MSP5} will provide a nearly constant current to bias M_{SP2} . Without I_{MSP5} ,

 M_{SP2} may be in triode region when M_{SP1} senses a very small current. Under a condition like this, the feedback loop may be unstable. By adding a compensation capacitor CC1, and appropriately biasing M_{SP2} , the problem of stability can be resolved.



Figure 2.5 Schematic of M1 short circuit protection

MOS	M1	MSP0	MSP1	MSP2	MSP3	MSP4	MSP5	MSP6			
W/L(µm)	106/3	6/3	6.6/50	6/12	6/12	6/3	6/3	50/3			
Μ	198	2	1	1	1	12	4	10			
MOS	MEP1	MEP2	MEP3	MEP4	MEP5	MC1	MC2	MC3			
W/L(µm)	6/4	6/4	6/6	6/6	6/3	6/2.5	6/2.5	6/2.5			
Μ	1	1	1	1	1	1	1	1			
MOS	MC4	MC5		•	•		•				
W/L(µm)	6/3	6/3	IB=5uA								
Μ	1	1		CC1=0.5P							

Table 2-4 Transistors W/L ratio of Fig.2.5



MOS	M2	MSN0	MSN1	MSN2	MSN3	MSN4	MSN5	MSN6
W/L(µm)	66/2.5	6/6	5/50	6/6	6/6	6/6	6/6	6/2.5
Μ	182	2	1	2	2	26	4	2
MOS	MEN1	MEN2	MEN3	MEN4	MEN5	MC1	MC2	MC3
W/L(µm)	6/6	6/6	6/6	6/6	6/6	6/2.5	6/2.5	6/2.5
Μ	1	1	1	1	2	1	1	1
MOS	MC4	MC5		•	•		•	
W/L(µm)	6/3	6/3	IB=5uA					
М	1	1			CC2=	=0.5P		

Table 2-5 Transistors W/L ratio of Fig.2.6

 M_{SP1} , M_{SP2} , M_{SP3} , and M_{SP4} can be considered as a current comparator. The transistor M_{SP2} mirrors a constant current from M_{SP0} , and M_{SP1} senses a current from M_1 . When I_{SP1} is bigger than the set current I_{SP4} , M_{SP3} will be in triode region, and the voltage at node SW_P will be pulled down to turn on the transistor M_{SP6} . As M_{SP6} is turned on, the source-gate voltage of M1 will be limited, which enables the function of short circuit protection.

When designing a circuit as shown in Fig.2.5, we will probably focus on the condition where Vout > Vref, under which M1 is turned on. Otherwise, when $V_{OUT} < V_{REF}$, the Class-AB output stage will cutoff M1. However, we shall not neglect the effects of the circuit where $V_{OUT} < V_{REF}$. When V_{OUT} is much lower than V_{REF} , the drain-source voltage of M_{SP5} is much higher than its gate-source voltage. Considering channel length modulation, I_{MSP5} may become larger than I_{MSP4} . When the system starts, the voltages at all nodes will be V_{SS} in the beginning. After M1 charges node OUT for a short period of time, V_{OUT} reaches V_{REF} . If I_{MSP5} gets larger than I_{MSP4} due to channel length modulation, M_{SP6} will be turned on, which cuts off M1 and consequently stops it from charging node OUT. All these reactions will result in a deadlock. Therefore, the criteria for enabling short circuit protection is

 $I_{MSP1(Sen \sin g)} > I_{MSP4} - I_{MSP5}$. That is to say, I_{MSP4} and I_{MSP5} should not be set compatible in case of malfunction.



Figure 2.7 Schematic of pre-amplifier using in Fig.2.2

MOS	M0	M1	M2	M3	M4	M5	M6	M7	
W/L(µm)	6/6	6/20	6/20	6/6	6/6	6/6	6/6	6/6	
Μ	2	10	10	2	2	4	30	30	
MOS	MC1	MC2	MC3	MC4	IB=1uA				
W/L(µm)	6/2.5	6/2.5	6/2.5	6/3	R1=40K				
Μ	1	1	1	1	C1=1.5P				

Table 2-6 Transistors W/L ratio of Fig.2.7

2.3.4 Frequency compensation

The circuit proposed in this thesis is applied to the audio band. Human ears respond to sound vibrations frequencies between 200Hz and 20KHZ. It is there anticipated that bandwidth is probably not the main concern for an audio amplifier. Take the specifications in Table 1-1 for example, since the design target for Unit Gain Bandwidth is merely0.6MHz, a common two-stage amplifier as shown in Fig.2.7 as the pre-amplifier will do. This pre-amplifier is designed with a high DC gain and a low bandwidth (0.8MHz). The buffered output stage as discussed in Sec. 2.3.2. is designed with a dominant pole 10 times larger than the unit gain frequency of the pre-amplifier, which saves the complex problem of frequency compensation.

To simplify the stability analysis of the buffered output stage, that $pole \approx \frac{1}{2\pi RC}$ is appropriated here. The circuit shown in Fig.2.3 contains several poles, including nodes, P1, P2, P3, P4, P5, EP_OUT, and OUT. Consider this transistor size listed in table 2-2. The power transistor M1 must be large enough to drive a desired output power, and transistors M_{P11}, M_{P11B}, M_{P12} can't be too small to define the quiescent current. Therefore, the parasitical capacitance at node EP_OUT will be the maximum. To obtain a higher gain in the differential pair, M_{P1} and M_{P2} are usually chosen of a larger size. We can therefore derive the comparisons of parasitical capacitance at these nodes from the size of each transistor as

$$OUT > EP \quad OUT > P1 > P2 > P5 > P3 > P4$$
. (2.22)

Although node OUT carries the biggest parasitical capacitance, it is connected to a resistors as small as 8 Ohm that helps push its pole to the high frequency domain. As a result, the order of poles at all node in the frequency domain will be

$$EP _OUT < P1 \approx P2 < P5 < P3 \approx P4 < OUT .$$

$$(2.23)$$

As mentioned earlier that M_{SP13} will be cutoff as the voltage V_{OUT} increases, it will change the equivalent resistance at EP_OUT from $\frac{1}{g_{mP13}}$ to $(r_{O,P9} // r_{O,P11})$, and the pole of EP_OUT will thus move to the lower frequency domain. Therefore, it should be carefully considered whether the moved dominate pole would affect the stability of the pre-amplifier.



R1=480K	R2=90K	R3=120K	R4=90K	R5=70K	R6=50K
R7=40K	R8=30K	R9=20K	R10=20K	R11=30K	

Figure 2.8 Schematic of Volume control circuit

MOS	M0	M1	M2	M3	M4	M5	M6	M7
W/L(µm)	5/8	5/10	5/10	5/8	5/8	5/8	5/8	5/8
Μ	2	10	10	1	1	2	20	20
MOS	MC1	MC2	MC3	MC4	IB=1uA			
W/L(µm)	5/2.5	5/2.5	5/2.5	5/3	R1=0			
Μ	1	1	1	1	C1=0.7P			

Table 2-7 An alternative list of W/L ratio of transistors in Fig.2.7.

2.4 Volume control circuit

Fig.2.8 shows the block diagram of the Volume control circuit which is made up of an inverting feedback OPAMP and 9 transmission gates. The schematic of the OPAMP is the same as Fig.2.7, but the dimensions of transistors are different (See Table 2-7). When the switch of a transmission gate is active, the corresponding parallel resistor will become short circuited. When all the transmission gates are switched open, the inverting close loop gain of OPAMP reaches the maximum. As TG1 is active, its close loop gain decreases. When these transmission gates are inactivated in order, a 10 level volume control is therefore made possible.

Since human hearing is measured by the log scale, resistors in this design should be specially chosen so that the 10 level close loop gain is linear in log scale.

That is
$$\alpha \frac{R_2 + R_3 + \dots + R_{10} + R_{11}}{R_1} = \frac{R_3 + R_4 + \dots + R_{10} + R_{11}}{R_1}$$
,
 $\alpha \frac{R_3 + R_4 + \dots + R_{10} + R_{11}}{R_1} = \frac{R_4 + R_5 + \dots + R_{10} + R_{11}}{R_1}$,
...
 $\alpha \frac{R_{10} + R_{11}}{R_1} = \frac{R_{11}}{R_1}$, and so on.

Therefore, the fixed difference of each volume level is $20 \log \alpha$.

2.5 DC control 10 level volume

Fig.2.9 shows a simple analog to digital converter. Transistors, MS1~MS9, are mirrored current sources, which are connected to the corresponding NMOS, MV1~MV9, below, to form 9 inverters. By setting that the closer the NMOS is to the right in Fig2.10, the smaller W/L ratio it has, the respective switching voltage of the 9 inverters will be in order as a rising sequence. As VCON increases gradually, these 9 inverters will be switched on one by one. That is to say, one single DC Voltage VCON is enough to generate a set of 9 control signals, VC[1:9] and VCB[1:9], which is used to control the 9 transmission gates in Fig.2.8. On the other hand, inverters MS10 and MV10 are used as a control signal generator for the MUTE function. When VMUTE gets larger than 2.5V, BUF_EN exports signal 0, and BUF_ENB, 1. This will turn off power transistors M1 and M2 in Fig.2.2.

INV_C, as shown in Fig.2.9, is a inverter chain. It is illustrated in detail in Fig2.10. The INV_C as an inverter chain is used to make the switch signal transient very fast.



Figure 2.9 A simple Analog to Digital converter



Figure 2.10 Schematic of symbol INV_C shown in Fig.2.9

MOS	MB1	MB2	MS1	MS2	MS3	MS4	MS5	MS6
W/L(µm)	4/5	4/5	4/5	4/5	4/5	4/5	4/5	4/5
М	5	1	1	1	1	1	1	2
MOS	MS7	MS8	MS9	MS10	MV1	MV2	MV3	MV4
W/L(µm)	4/5	4/5	4/5	4/5	4/2.5	4/3	4/4	4/6.5
М	2	3	3	1	20	2	2	1
MOS	MV5	MV6	MV7	MV8	MV9	MV10	M1	M2
W/L(µm)	4/14	4/12.5	4/19	4/18	4/24	4/15	5/4	5/4.7
М	1	1	1	1	1	1	2	1
MOS	M3	M4	M5	M6			•	
W/L(µm)	5/5	5/5	5/5	5/5	IB1=2uA			
М	1	1	1	1	IB2=2uA			

 Table 2-8 Transistors W/L ratio of Fig.2.9 and Fig.2.10



MOS	M0	M1	M2	M3	M4	M5	M6	M7
W/L(µm)	5/12	5/9	5/9	5/9	5/9	5/12	5/9	5/12
Μ	2	4	4	2	2	2	4	2
MOS	M8	M9	M10	M11	MST1	MST2	MST3	MST4
W/L(µm)	20/4	20/4	20/4	20/4	5./3	5/25	32/5	5/2.5
Μ	2	8	2	8	1	1	18	1
MOS	MC1	MC2	MC3	MC4	MC5	MC6	IB=5uA	
W/L(µm)	5/25	5/25	5/25	5/25	5/25	5./3		
Μ	1	1	1	1	1	1		

 Table 2-9 Transistors W/L ratio of Fig.2.11.

2.6 Reference voltage generator

In Fig.2.1, we use two diode connecting PMOS to generate the reference voltage, $V_{MID} = \frac{V_{DD} - V_{SS}}{2}$. Any current flowing out or into VMID will change its voltage. This is why we need the unit gain buffer, OP_{VREF}. Usually, a very large capacitor is used to connect VREF and VSS to avoid unexpected interference from the power supply. According to the application notes of TDA7496L, a 470uF capacitor is advised. Fig.2.11 shows the amplifier, OPVREF, with a common-drain output stage. With an output capacitor load so big as 470uF, the output node of the amplifier will be the dominate pole in frequency domain. Consider the transient at the start. It may take a very long time to charge the 470uF capacitor load to the required voltage, $\frac{V_{DD} - V_{SS}}{2}$. Transistors MST1-MST4 are therefore used to shorten the charging time. When the system is shut down, the control signals will be EN=Low, ENB=High. All of the voltage at node N1, N2, N3, N4, MID, OUT will be Low, too. However, when the system starts, the control signal is reversed, and the VMID will be high enough to trigger the inverter, MST1 and MST2, to turn on transistor MST3. Before the voltage VOUT is charged to $\frac{V_{DD} - V_{SS}}{2}$, VSW will be reversed again, and turn off MST3.

CHAPTER 3

Simulation result and discussion

3.1 Chip layout

The chip of our design is fabricated by the UMC 0.5um +/-20V2P2M high voltage process. To be economical, we only use two layers of metal. The chip dimension is 2210um x 3497um as shown in Fig.3.1, and Fig.3.2 shows its function blocks accordingly.



Figure 3.1 Chip layout view



Figure 3.2 Chip layout view and its according function blocks

VSS	ZZZZ PIN1	PIN28	VSS	
VSS			VSS	
VSS			VSS	Original function
IN L			OUT L	pin of TDA7496L
ER L			VDD	
VOL			VDD	
ER R	77772		OUT R	
NC			VSS	
IN R			MUTE	
VREF			STBY	
VDD			BIAS	
OUT			VIN1	Added test pin
VSS			VIN2	
NC	PIN14	PIN15	NC	

Figure 3.3 Pin Connection after packaging

3.2 Pre-Simulation result and Monte Carlo analysis

(1) Buffered amplifier

Frequency Response of buffered amplifier					
		VDD=10V VDD=18V			
FF	Gain	108 dB	113dB		
۲۲ ۵°С	PM	96°	99°		
	GB	0.63 MHz	0.99MHz		
тт	Gain	103dB	109dB		
11 30°C	PM	87°	91°		
500	GB	0.63MHz	0.74MHz		
55	Gain	101dB	108dB		
55 70°C	PM	84°	77°		
	GB	0.45 MHz	0.54MHz		

With $R_L=8\Omega$, $C_L=30pF$

Table 3-1. The frequency response

 pre-simulation result of buffered amplifier

Quiescent current of buffered amplifier				
	VDD=10V	VDD=18V		
FF 70℃	9.1mA	12mA		
TT 30℃	7.6mA	11mA		
SS 0℃	7.6mA	9.5mA		

With $R_L = 8\Omega$, $C_L = 30 pF$

Table 3-2. The quiescent currentpre-simulation result of buffered amplifier

- # # # # # # .					
The output peak current of power MOS					
	M1	M2			
FF 0°C	1.15A	0.95A			
TT 30°C	1.05A	1.13A			
SS 70°C	0.91A	0.82A			

VDD=14V R_L=0.01Ω, C_L=30pF

Table 3-3 The Output peak current of power MOS

<Monte Carlo Analysis>

We will refer to Monte Carlo Analysis and paper [13] to evaluate how big an impact mismatching would have on quiescent current. (3.1) and (3.2) show that the error of threshold voltage is inversely proportional to the square root of the MOS size.

$$\Delta V_{\rm TH} = \frac{A_{\rm VTH}}{\sqrt{\rm WL}} \tag{3.1}$$

$$\frac{\Delta\beta}{\beta} = \frac{A_{\beta}}{\sqrt{WL}}, \quad \beta = \mu C_{\text{ox}} \frac{W}{L}$$
(3.2)

Set A_{β} to be 10%, and A_{β} is hereby derived by Vth in Table 3-4. Fig.3.4 shows the error percentage of quiescent current yielded by mismatching out of 100 Monte Carlo Analyses.

Dovido	Delta-V _{th} in different Corner			
Device	SS	ТТ	FF	
Symmetry HVNMOS	0.182	0	-0.182	
Asymmetry HVNMOS	0.178	0	-0.178	
Symmetry HVPMOS	-0.291	0	0.291	
Asymmetry HVPMOS	-0.340	0	0.340	

Table 3-4 The value of Delta-Vth for differenttransistors and corners of the UMC process





Figure 3.4 The quiescent Monte Carlo analysis of buffered amplifier

(2) Total harmonic distortion



Figure 3.5 The Pre-simulation result of total harmonic distortion



3.3 Post-Simulation result

(1) Buffered amplifier

Frequency response of buffered amplifier						
		Pre-Sim	ulation	Post-Simulation		
Supply voltage		VDD=10V	VDD=18V	VDD=10V	VDD=18V	
	Gain	108 dB	113dB	109dB	115dB	
гг 0°С	PM	96°	99°	81°	81°	
	GB	0.63 MHz	0.99MHz	1.29MHz	1.50MHz	
ТТ	Gain	100dB	106dB	104dB	110dB	
11 30°C	PM	70°	70°	72°	75°	
300	GB	0.75MHz	0.79MHz	0.67MHz	0.80MHz	
55	Gain	101dB	108dB	106dB	112dB	
55 70°C	PM	84°	77°	59°	60°	
70 C	GB	0.45 MHz	0.54MHz	0.46MHz	0.50MHz	
With $R_L=8\Omega$, $C_L=30pF$						

 Table 3-5
 The frequency response

post-simulation result of buffered amplifier



Figure 3.7 The PSRR- of the buffered amplifier

(2) Total harmonic distortion



Figure 3.8 The post-simulation of total harmonic distortion



(3) Volume control amplifier

Frequency Response					
	VDD=10V VDD=18V				
БĿ	Gain	103dB	109dB		
гг 0°С	PM	72°	73°		
	GB	1.01MHz	1.02MHz		
ТТ 30℃	Gain	100dB	106dB		
	PM	71°	72°		
	GB	0.73MHz	0.78MHz		
SS	Gain	98dB	103dB		
55 70℃	PM	59°	60°		
	GB	0.64MHz	0.63MHz		
		With C _L =3pF			

Table 3-6 The frequency response post-simulationresult of the volume control amplifier shown in



Figure 3.9 VC[1]~VC[9] vs. V_{CON} DC transfer function



(5) Amplifier for VREF

Frequency Response					
	VDD=10V VDD=18V				
FF	Gain	72dB	103dB		
гг 0°С	PM	81°	72°		
	GB	4.4KHz	1.01MHz		
ТТ 30℃	Gain	66dB	106dB		
	PM	82°	73°		
	GB	2.1KHz	0.71MHz		
SS	Gain	57dB	65dB		
55 70℃	PM	83°	59°		
	GB	0.7KHz	1.7KHz		
		With C _L =470pF			

Table 3-7 The frequency response post-simulationresult of the amplifier shown in Fig.2.11

(6) Conclusions of simulation

Table 3-8 shows that the post simulation result of this work is better than the design specification which is refers to TDA-7496L. Also, Fig.3.10 and 3.11 show the relationship between supply voltage and out power. Compared with TDA-7496L, this chip can drive larger output power under the same supply voltage.

Symbol	Parameter	Test condition	SPEC.	Post-sim.	Unit
Vs	Supply voltage range		10~18	10~20	V
Iq	Total quiescent current		<50	20	mA
Po	Output power	THD=1%, R_L =8 Ω	>1.3	1.84	W
THD	Total harmonic distortion	P _O =1W, f=1kHz	<0.4	0.073	%
BW	Unit gain bandwidth	ESA	>0.6	0.72	MHz
Ipeak	Out peak current		<1.2	<1.10	А
PSRR	Power supply rejection ratio	F=1kHz	>50	63	dB

(Testing condition $Vs = 14V$; $RL = 8\Omega$, Temp=25° C)
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Table 3-8 The comparison of post-simulation result and design spec.



Figure 3.10 Output power vs. supply voltage (TDA7496L)



3.4 Discussion

Under packaging, audio amplifiers with a large output power must deal with the problem of heat radiation; otherwise the chip will be over-heated. Our chip is packaged by SSOP28 process, as shown in Fig.4.4., where several ground pins are used to help with heat radiation. Compared with TDA7496L, our chip makes use of 8 more pins due to the existence of the test amplifier, OP1C. From Fig.3.3., we can see that the output stage power transistors of the buffered amplifier take up quite some space. This is because we only use two layers of metal and, to meet the required current density of the metal layer according to the UMC layout rule, we have to save much space for the metal layer. Meanwhile, it is rather convincing that, with just one more metal layer, we would size down the chip significantly and rearrange the layout of power transistors more efficiently.

CHAPTER 4

Conclusions and future work

4.1 Conclusions

This thesis, consulting the specifications in business industry, has put forth a high power, high linearity audio amplifier with complete features of volume control, mute mode, standby mode, and earphone output. The newly proposed error amplifiers, when used in Class-AB quasi-complementary output stage, prove to be highly applicable in well defining the quiescent current and saving it from the influence of offset voltage. Moreover, since the gain of error amplifiers increases accordingly with the augmentation of the output swing, we therefore derive better linearity with a high output power. From Table 3-14, it is simple to draw a comparison between our design and TDA7469L that we have a much smaller THD under the same output power. Besides, compared to the structures proposed in some other papers[6][7][8], since the amplifiers in our design have a large output swing, smaller-size power transistors will therefore suffice to reach the desired output power. Compare our structure specifically with that in reference [7], even though the error amplifier we proposed needs a slightly larger bias current, our structure is by far more applicable to the supply voltage of a much wider range.

4.2 Future work

Layout of the chip in discussion here has been completed; however, the process provider failed to schedule the fabrication in time. We therefore need to acquire detail measurements to verify whether the actual performance conforms to the post-simulation results. Besides,

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although the fabrication process in use here guarantees a maximum supply voltage of 40V, this is done at the expense of certain characteristics of transistors. Restricted by packaging, we only came out with a design of a maximum output power of 2W, and a maximum supply voltage, 18V. It is a shame to underuse a fabrication process as such. Given the opportunity to apply a more suitable fabrication process with a maximum supply voltage of 20V, we are confident to size down the chip significantly and achieve even better performance.

Our structure provides a bandwidth sufficient enough for audio frequency band, though still not large enough for other applications. As discussed in section 2.3.4., the output stage is designed with a dominant pole 10 times larger than the unit gain frequency of the pre-amplifiers. In our design, it is difficult to locate an output stage dominant pole at a higher frequency domain since we have to at the same time take into account both a high output power and high linearity performance. This is not only the reason why the bandwidth of our structure is limited, but also a direction in which we may consider improving our structure in the future.

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